

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Xuming XIE</td> <td>11/29/2012</td> </tr> <tr> <td>Haruhisa MASUDA</td> <td>11/29/2012</td> </tr> </tbody> </table>		Name	Execution Date	Xuming XIE	11/29/2012	Haruhisa MASUDA	11/29/2012				
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<table border="1"> <tr> <td>Name:</td> <td>TSINGHUA UNIVERSITY</td> </tr> <tr> <td>Street Address:</td> <td>Qinghuayuan, Haidian District</td> </tr> <tr> <td>City:</td> <td>Beijing</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>100084</td> </tr> </table>		Name:	TSINGHUA UNIVERSITY	Street Address:	Qinghuayuan, Haidian District	City:	Beijing	State/Country:	CHINA	Postal Code:	100084
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<table border="1"> <tr> <td>Name:</td> <td>DAIKIN INDUSTRIES, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>Umeda Center Building, 4-12, Nakazaki-Nishi 2-Chome, Kita-ku</td> </tr> <tr> <td>City:</td> <td>Osaka-Shi, Osaka</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>5308323</td> </tr> </table>		Name:	DAIKIN INDUSTRIES, LTD.	Street Address:	Umeda Center Building, 4-12, Nakazaki-Nishi 2-Chome, Kita-ku	City:	Osaka-Shi, Osaka	State/Country:	JAPAN	Postal Code:	5308323
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13808039</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13808039						
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Application Number:	13808039										
CORRESPONDENCE DATA											
Fax Number:	2022937860										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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OP \$40.00 13808039

ATTORNEY DOCKET NUMBER:	Q142668
NAME OF SUBMITTER:	Byron F. Galvez, New Apps Spec
Total Attachments: 4 source=Q142668_ASSIGNMENT_AS_FILED#page1.tif source=Q142668_ASSIGNMENT_AS_FILED#page2.tif source=Q142668_ASSIGNMENT_AS_FILED#page3.tif source=Q142668_ASSIGNMENT_AS_FILED#page4.tif	

Assignment

Whereas, We, Xuming XIE c/o TSINGHUA UNIVERSITY, Qinghuayuan, Haidian District, Beijing 100084 CHINA; and Haruhisa MASUDA c/o DAIKIN INDUSTRIES, LTD., Yodogawa Plant, 1-1, Nishihitotsuya, Settsu-shi, Osaka 5668585, JAPAN, hereinafter called assignors, have invented certain improvements in RESIN COMPOSITION AND MOLDED ARTICLE and executed an application for Letters Patent of the United States of America therefor on _____; and

Whereas, jointly, each taking an undivided one-half interest in the above-mentioned application,

TSINGHUA UNIVERSITY of Qinghuayuan, Haidian District, Beijing 100084, CHINA
and

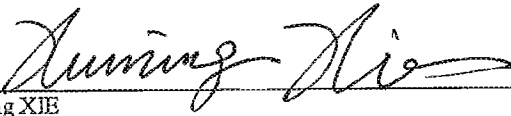
DAIKIN INDUSTRIES, LTD., of Umeda Center Building, 4-12, Nakazaki-Nishi 2-Chome, Kita-ku, Osaka-Shi, Osaka 5308323, JAPAN

(assignees), desire to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

We, the above named assignors, hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, including the right to claim priority under 35 U.S.C. §119, and we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignees.

We hereby authorize and request our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, NW, Washington, DC 20037-3213 to insert here in parentheses (Application number 13/808,039 and Confirmation number 4975, filed January 2, 2013) the application number, confirmation number and filing date of said application when known.

Date: NOV. 29. 2012 
s/Xuming XIE

Date: _____
s/Haruhisa MASUDA

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

Assignment

Whereas, We, Xuming XIE c/o TSINGHUA UNIVERSITY, Qinghuayuan, Haidian District, Beijing 100084 CHINA; and Haruhisa MASUDA c/o DAIKIN INDUSTRIES, LTD., Yodogawa Plant, 1-1, Nishihitotsuya, Settsu-shi, Osaka 5668585, JAPAN, hereinafter called assignors, have invented certain improvements in RESIN COMPOSITION AND MOLDED ARTICLE and executed an application for Letters Patent of the United States of America therefor on _____; and

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and

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2011 P00126
DA906US

Date:

s/Xuming XIE

Date:

NOV. 29. 2012 Haruhisa Masuda

s/Haruhisa MASUDA

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